

BMD-S00_evaj.pcb 4145 S014-TT-TT 18:18:45S uicpoTac \$

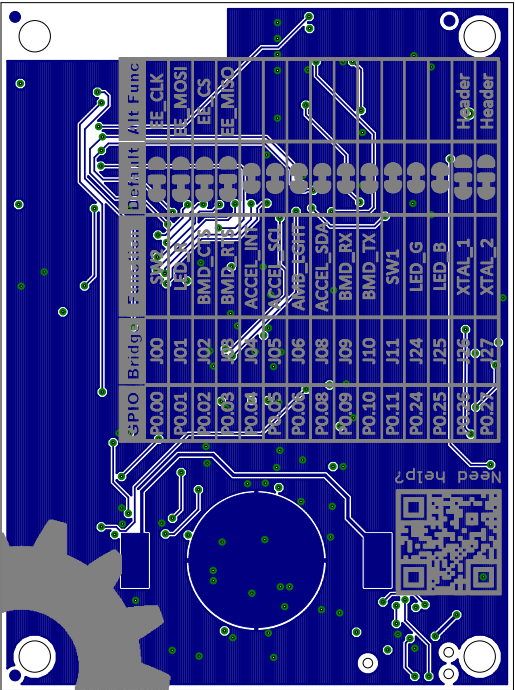
Дата: TT\TT\S014 3:45:58 PM	Sheet: 1	
События: S014 Bridge, LLC	3-T	БЕН:

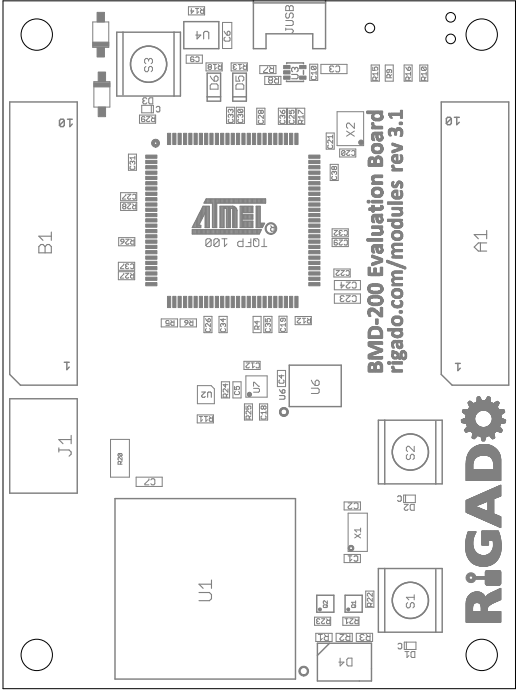
TITLE: BMD-S00_evaj

Bridge, LLC

Layer 4	Bottom Copper, 1 oz, 1.32mil TX958, 5x1080, 0.0175mil Inner Copper, 1 oz, 1.32mil
Layer 3	Inner Layer core, 0.058mil Inner Copper, 1 oz, 1.32mil TX958, 5x1080, 0.0175mil Job Copper, 1 oz, 1.32mil
Layer 5	
Layer 1	

4 LAYER PCB STACKUP, ~0.085", finished thickness





4 LAYER PCB STACKUP, ~0.062” finished thickness

Layer 1
Layer 2
Layer 3
Layer 4

Top Copper 1 oz, 1.35mil
1x7628, 2x1080, 0.0119inch
Inner Copper 1 oz, 1.35mil
Inner layer core, 0.028inch
Inner Copper 1 oz, 1.35mil
1x7628, 2x1080, 0.0119inch
Bottom Copper 1 oz, 1.35mil

Rigado, LLC		
TITLE: BMD-200_eval		
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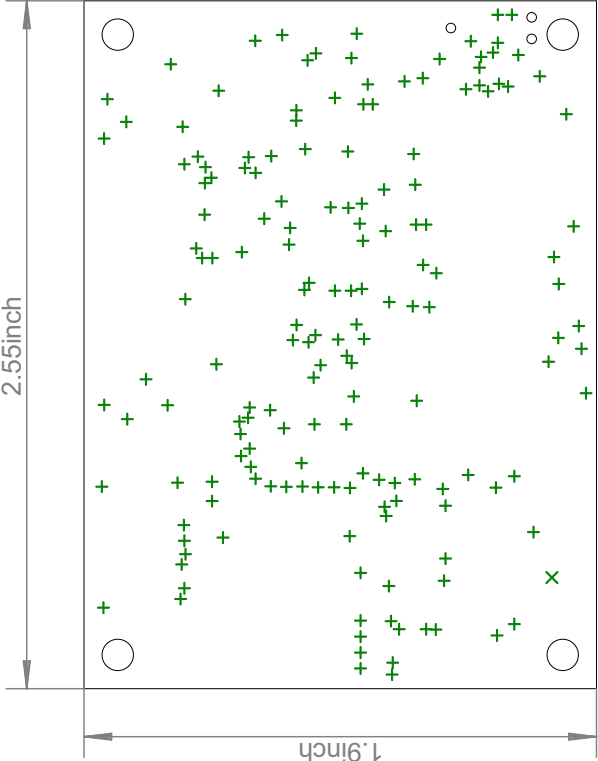
Дата: TT\TT\S0T4 3:45:58 бл	Sheet: 1
События: S0T4 Bridge, LLC	3.1 REN:

TITLE: BMD-500_eval

Bridge, LLC

Layer 4	Bottom Copper, 1 oz, 1.32mil TXN58, 5x1080, 0.017aipc Inner Copper, 1 oz, 1.32mil
Layer 3	Inner Layer core, 0.058aipc Inner Copper, 1 oz, 1.32mil TXN58, 5x1080, 0.017aipc Job Copper, 1 oz, 1.32mil
Layer 5	
Layer 1	4 LAYER PCB STACKUP, ~0.085", finished thickness

GPIO	Bridge	Function	Default	Alt Func
P0.00	J00	SW2		EE_CLK
P0.01	J01	LED_R		EE_MOSI
P0.02	J02	BMD_CTS		EE_CS
P0.03	J03	BMD_RTS		EE_MISO
P0.04	J04	ACCEL_INT		
P0.05	J05	ACCEL_SCL		
P0.06	J06	AMB_LIGHT		
P0.08	J08	ACCEL_SDA		
P0.09	J09	BMD_RX		
P0.10	J10	BMD_TX		
P0.11	J11	SW1		
P0.24	J24	LED_G		
P0.25	J25	LED_B		
P0.26	J26	XTAL_1		Header
P0.27	J27	XTAL_2		Header



Sym	Nº	Mils	MM	Qty	Plated
+	1	8	0.20	165	YES
x	2	20	0.51	1	YES
▣	3	35	0.89	3	NOT
◇	4	116	2.95	4	NOT

- NOTES: UNLESS OTHERWISE SPECIFIED
1. FABRICATE TO MEET OR EXCEED THE REQUIREMENTS OF IPC 6011/6012 CLASS 2, AS DEFINED IN IPC-2221
 2. PREPREG MATERIAL: MATERIAL WITH TG > 170
 3. MINIMUM TRACE WIDTH IS .006, MINIMUM SPACING IS .006
 4. BOARD FINISH: ELECTROLESS NICKEL, IMMERSION GOLD (ENIG).
 5. FLAMMABILITY: MATERIALS TO MEET UL94V-0 SPECIFICATION.
 6. APPLY LPI SOLDERMASK (BLUE) ON BOTH SIDES.
 7. SILKSCREEN ON BOTH SIDES USING WHITE EPOXY INK, REGISTRATION TO BE .01. CLEAR SILKSCREEN FROM ALL EXPOSED PADS.
 8. THE FABRICATED BOARD SHALL BE ROHS COMPLIANT.

4 LAYER PCB STACKUP, ~0.062” finished thickness

Layer 1	Top Copper 1 oz, 1.35mil
Layer 2	1x7628, 2x1080, 0.0119inch
Layer 3	Inner Copper 1 oz, 1.35mil
Layer 4	Inner layer core, 0.028inch

Inner Copper 1 oz, 1.35mil
1x7628, 2x1080, 0.0119inch
Bottom Copper 1 oz, 1.35mil

Rigado, LLC

TITLE: BMD-200_eval

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